L Number	Hits	Search Text	DB	Time stamp
3	0	("863030.ap.").PN.	USPAT;	2003/03/27
	ŭ	(000000.ap.)	US-PGPUB;	11:23
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	3	863030.ap.	USPAT;	2003/03/27
			US-PGPUB;	11:46
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	2	("5451818").PN.	USPAT;	2003/03/27
			US-PGPUB;	12:04
			EPO; JPO;	
			DERWENT;	
		/ manage	IBM_TDB	0000/00/07
6	0	("MMIC.ti,ab,clm. and thick adj film adj	USPAT;	2003/03/27
		capacitor").PN.	US-PGPUB;	12:04
			EPO; JPO;	[
			DERWENT;	
7	1	MMIC.ti,ab,clm. and thick adj film adj	IBM_TDB USPAT;	2003/03/27
'	+	capacitor	US-PGPUB;	12:11
		Capacitor	EPO; JPO;	12.11
			DERWENT;	<u> </u>
			IBM TDB	<u> </u>
8	0	MMIC.ti,ab,clm. and air near2 (insulation	USPAT;	2003/03/27
	J	or isolation or isolate or insulate)	US-PGPUB;	12:12
		near12 (transmit or transmission) near12	EPO; JPO;	
		(receive or receiver)	DERWENT;]
			IBM_TDB	
9	0	MMIC.ti,ab,clm. and (spacing or air)	USPAT;	2003/03/27
		near2 (insulation or isolation or isolate	US-PGPUB;	12:13
		or insulate) near12 (transmit or	EPO; JPO;	
		transmission) near12 (receive or	DERWENT;	.
	_	receiver)	IBM_TDB	
10	0	MMIC same (spacing or air) near12	USPAT;	2003/03/27
		(insulation or isolation or isolate or	US-PGPUB;	12:15
		insulate) near12 (transmit or	EPO; JPO;	
		transmission) near12 (receive or	DERWENT;	1
11	1 2	receiver) (spacing or air) near12 (insulation or	IBM_TDB USPAT;	2003/03/27
11	13	isolation or isolate or insulate) near12	US-PGPUB;	12:16
		(transmit or transmission) near12	EPO; JPO;	
		(receive or receiver)	DERWENT;	
		(IBM TDB	
12	0	(spacing or air) near12 (insulation or	USPAT;	2003/03/27
		isolation or isolate or insulate) near12	US-PGPUB;	12:17
		(transmit or transmission) near12	EPO; JPO;	
1		(receive or receiver) and (257/\$6.ccls.	DERWENT;	
		or 438/\$6.ccls.)	IBM_TDB	
13	2	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/03/27
		isolation or isolate or insulate) near12	US-PGPUB;	12:19
ļ		(transmit or transmission) near12	EPO; JPO;	
i i	:	(receive or receiver) and (257/\$6.ccls.	DERWENT;	
14	1.0	or 438/\$6.ccls. or 455/\$6.ccls.)	IBM_TDB	2003/03/37
14	13	, , ,	USPAT;	2003/03/27
ĺ		isolation or isolate or insulate) near12	US-PGPUB;	17:05
		(transmit or transmission) near12	EPO; JPO;	
		(receive or receiver)	DERWENT; IBM TDB	
15	2	488721.ap.	USPAT;	2003/03/27
10	2	100/21.ap.	US-PGPUB;	13:12
			EPO; JPO;	****
			DERWENT;	
			IBM TDB	
			1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	1

16	37	LTCC and MMIC	USPAT; US-PGPUB;	2003/03/27 13:13
			EPO; JPO;	15.15
			DERWENT;	
			IBM_TDB	
17	0	LTCC near12 transfer adj tape and MMIC	USPAT;	2003/03/27
			US-PGPUB; EPO; JPO;	13:13
			DERWENT;	
			IBM_TDB	
18	4	LTCC and transfer adj tape and MMIC	USPAT;	2003/03/27
			US-PGPUB;	13:18
			EPO; JPO; DERWENT;	
			IBM TDB	
19	4	LTCC and transfer adj tape and	USPAT;	2003/03/27
		(monolithic adj microwave adj integrated	US-PGPUB;	13:20
		adj circuit or MMIC)	EPO; JPO; DERWENT;	
			IBM TDB	
20	7	(low adj temperature adj co-fired adj	USPĀT;	2003/03/27
		ceramic or LTCC) and transfer adj tape	US-PGPUB;	14:43
		and (monolithic adj microwave adj integrated adj circuit or MMIC)	EPO; JPO; DERWENT;	
,		integrated adj circuit of Milc)	IBM TDB	
21	170	MMIC.ti,ab,clm. and capacitor same	USPAT;	2003/03/27
		resistor	US-PGPUB;	14:44
			EPO; JPO;	
			DERWENT; IBM TDB	
22	73	MMIC.ti,ab,clm. and capacitor same	USPAT;	2003/03/27
		resistor.ti,ab,clm.	US-PGPUB;	14:44
			EPO; JPO;	
			DERWENT; IBM TDB	
23	5	MMIC.ti,ab,clm. and capacitor same	USPAT;	2003/03/27
		resistor.ti,ab,clm. and	US-PGPUB;	14:45
		transceiver.ti,ab,clm.	EPO; JPO;	
			DERWENT; IBM TDB	
24	1427	((257/277) or (257/728) or	USPAT;	2003/03/27
		(455/73)).CCLS.	US-PGPUB;	17:07
			EPO; JPO; DERWENT;	
			IBM TDB	
25	81	(((257/277) or (257/728) or	USPAT;	2003/03/27
		(455/73)).CCLS.) and (mmic or monolithic	US-PGPUB;	17:10
		adj microwave adj integrated adj	EPO; JPO; DERWENT;	
		circuit).ti,ab,clm.	IBM TDB	
26	8	(((257/277) or (257/728) or	USPAT;	2003/03/27
		(455/73)).CCLS.) and (mmic or monolithic	US-PGPUB;	17:10
		adj microwave adj integrated adj circuit).ti,ab,clm. and transceiver	EPO; JPO; DERWENT;	
		cricuit, cr, ab, crm. and transcerver	IBM TDB	
_	0	mmic.ti. and transceiver.clm.	USPAT;	2002/10/20
			US-PGPUB;	16:25
			EPO; JPO; DERWENT;	
			IBM TDB	
-	15	mmic.ti. and transceiver	USPAT;	2002/09/14
			US-PGPUB;	14:12
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1	mmic.ti. and transceiver and (tuned or	USPAT;	2002/09/14
		tuning)	US-PGPUB;	14:13
			EPO; JPO;	
			DERWENT; IBM TDB	
	<u></u>	<u>l</u>]

-	0	mmic.ti. and transceiver.ti,ab,clm. and (tuned or tuning).ti,ab.clm.	USPAT; US-PGPUB; EPO; JPO;	2002/09/14 14:15
			DERWENT;	
_	2	(mmic or microwave adj monolithic).ti.	IBM_TDB USPAT;	2002/09/14
		and transceiver.ti,ab,clm. and (tuned or tuning).ti,ab.clm.	US-PGPUB; EPO; JPO; DERWENT;	14:44
			IBM_TDB	
_	0	(mmic or microwave adj monolithic).ti. and transceiver.ti,ab,clm. and	USPAT; US-PGPUB;	2002/09/14
		438/\$6.ccls.	EPO; JPO; DERWENT; IBM TDB	
-	20	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2002/09/14
		and 438/\$6.ccls.	US-PGPUB; EPO; JPO;	14:44
			DERWENT; IBM_TDB	
_	370	integrated adj circuit adj board.ti.	USPAT; US-PGPUB;	2002/09/17
			EPO; JPO;	12.07
			DERWENT; IBM TDB	
_	7	integrated adj circuit adj board.ti. and	USPAT;	2002/09/17
		integrated adj circuit adj board.clm.	US-PGPUB; EPO; JPO;	12:08
			DERWENT;	
_	634	(455/73).CCLS.	<pre>IBM_TDB USPAT;</pre>	2002/10/20
		(100,70,10020.	US-PGPUB;	16:25
			EPO; JPO; DERWENT;	
		/	IBM_TDB	
_	147	(257/277).CCLS.	USPAT; US-PGPUB;	2002/10/20
			EPO; JPO;	10.23
			DERWENT; IBM TDB	
-	551	(257/728).CCLS.	USPAT;	2002/10/20
			US-PGPUB; EPO; JPO;	16:26
			DERWENT;	
_	1978	(mmic or monolithic adj microwave adj	IBM_TDB USPAT;	2002/10/20
		integrated adj circuit).ti,ab,clm.	US-PGPUB;	16:26
			EPO; JPO; DERWENT;	
_	1225	///55/72\ 0070 \ //057/077\ 0070 \	IBM_TDB	
	1325	((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.)	USPAT; US-PGPUB;	2002/10/20
			EPO; JPO;	
			DERWENT; IBM TDB	
-	70	((mmic or monolithic adj microwave adj	USPAT;	2002/10/20
		integrated adj circuit).ti,ab,clm.) and (((455/73).CCLS.) or ((257/277).CCLS.) or	US-PGPUB; EPO; JPO;	16:27
		((257/728).CCLS.))	DERWENT;	
_	3233	((mmic or monolithic adj microwave adj	<pre>IBM_TDB USPAT;</pre>	2002/10/20
		integrated adj circuit).ti,ab,clm.) or	US-PGPUB;	16:27
		(((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.))	EPO; JPO; DERWENT;	
_	221		IBM_TDB	
_	221	(((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) or	USPAT; US-PGPUB;	2002/10/20 16:28
		(((455/73).CCLS.) or ((257/277).CCLS.) or	EPO; JPO;	10.20
		((257/728).CCLS.))) and transceiver.ti,ab,clm.	DERWENT; IBM TDB	

-	4	((((mmic or monolithic adj microwave adj	USPAT;	2002/10/20
	-	integrated adj circuit).ti,ab,clm.) or	US-PGPUB;	16:29
		(((455/73).CCLS.) or ((257/277).CCLS.) or	EPO; JPO;	
		((257/728).CCLS.))) and	DERWENT;	
		transceiver.ti,ab,clm.) and transfer adj	IBM TDB	
		tape		
_	2	, -	USPAT;	2002/10/20
			US-PGPUB;	17:13
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	2	("6124636").PN.	USPAT;	2002/10/20
			US-PGPUB;	17:14
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	13	"5423080"	USPAT;	2002/10/20
			US-PGPUB;	17:14
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	2	("5423080").PN.	USPAT;	2002/10/20
			US-PGPUB;	17:14
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	18	(US-5423080-\$ or US-6124636-\$ or	USPAT;	2002/10/20
		US-6424074-\$ or US-6124765-\$ or	US-PGPUB;	17:34
		US-6278337-\$ or US-6278159-\$ or	DERWENT	
		US-5545924-\$ or US-6268779-\$ or		
		US-6073484-\$ or US-6441449-\$ or		
		US-6201728-\$ or US-6257058-\$).did. or		
		(US-20010001224-\$).did. or (EP-712534-\$		
		or EP-504020-\$ or JP-11214578-\$ or		
		WO-200075762-\$ or WO-200223674-\$).did.		
_	1	((US-5423080-\$ or US-6124636-\$ or	USPAT;	2002/10/20
		US-6424074-\$ or US-6124765-\$ or	US-PGPUB;	17:35
		US-6278337-\$ or US-6278159-\$ or	DERWENT	
		US-5545924-\$ or US-6268779-\$ or		
		US-6073484-\$ or US-6441449-\$ or		
		US-6201728-\$ or US-6257058-\$).did. or		
		(US-20010001224-\$).did. or (EP-712534-\$		
		or EP-504020-\$ or JP-11214578-\$ or		
		WO-200075762-\$ or WO-200223674-\$).did.)		
		and transfer adj tape		
-	2724	mmic or monolithic adj microwave adj	USPAT;	2002/10/20
		intergated adj circuit and transfer adj	US-PGPUB;	17:35
		tape	DERWENT	
-	5	\ \	USPAT;	2002/10/20
		integrated adj circuit) and transfer adj	US-PGPUB;	17:36
		tape	DERWENT	
-	19	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2002/10/20
		US-5423080-\$ or US-6124636-\$ or	US-PGPUB;	19:33
		US-5545924-\$ or US-6257058-\$ or	DERWENT	
		US-6278159-\$ or US-6278337-\$ or		
		US-6201728-\$ or US-6124765-\$ or		
		US-6424074-\$ or US-6073484-\$ or		
		US-6268779-\$).did. or		
	I	(US-20010001224-\$).did. or (EP-504020-\$		
	 	l '		•
		or JP-11214578-\$ or EP-712534-\$ or WO-200223674-\$ or WO-20075762-\$).did.		

-	8	((00 0101010	USPAT;	2002/10/20
		US-5423080-\$ or US-6124636-\$ or	US-PGPUB;	20:05
		US-5545924-\$ or US-6257058-\$ or	EPO; JPO;	
		US-6278159-\$ or US-6278337-\$ or US-6201728-\$ or US-6124765-\$ or	DERWENT;	
		US-6424074-\$ or US-6073484-\$ or	IBM_TDB	
		US-6268779-\$).did. or		
		(US-20010001224-\$).did. or (EP-504020-\$		
		or JP-11214578-\$ or EP-712534-\$ or		
		WO-200223674-\$ or WO-200075762-\$).did.)		
		and thickness		
-	18	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2002/10/20
		and ((thick or thickness) same mil)	US-PGPUB;	20:07
			EPO; JPO;	
			DERWENT;	
_	0	(monolithic add microscope on mmic) ti	IBM_TDB	2222 (12 (22
		(monolithic adj microwave or mmic).ti. and ((thick or thickness) near12 mil	USPAT;	2002/10/20 20:08
:		near12 base)	US-PGPUB; EPO; JPO;	20:08
		near 12 Base,	DERWENT;	
			IBM TDB	
_	17	(monolithic adj microwave or mmic).ti.	USPAT;	2002/10/20
		and ((thick or thickness) near12 mil)	US-PGPUB;	20:12
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	25	cte near4 gaas	USPAT;	2002/10/20
	ĺ		US-PGPUB;	20:50
			EPO; JPO;	
			DERWENT; IBM TDB	
-	2	("5451818").PN.	USPAT;	2002/10/20
		, , , , , , , , , , , , , , , , , , , ,	US-PGPUB;	20:50
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	2	("5451818").PN.	USPAT;	2002/10/21
	•		US-PGPUB;	07:56
			EPO; JPO;	
			DERWENT; IBM TDB	
_	o	("solder near3 MMIC adj chip").PN.	USPAT;	2002/10/21
		· · · · · · · · · · · · · · · · · · ·	US-PGPUB;	07:56
	;		EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	7	solder near3 MMIC adj chip	USPAT;	2002/10/21
			US-PGPUB;	08:12
			EPO; JPO; DERWENT;	
			IBM TDB	
-	3	silver adj epoxy near6 MMIC	USPAT;	2002/10/21
			US-PGPUB;	08:13
			EPO; JPO;	
			DERWENT;	
	_	må 1 mm m m m m m m m m m m m m m m m m	IBM_TDB	
-	3	silver adj epoxy near12 chip and	USPAT;	2002/10/21
		MMIC.ti, ab, clm.	US-PGPUB;	08:14
j			EPO; JPO;	
			DERWENT; IBM TDB	
-	5	silver adj epoxy near12 (die or chip) and	USPAT;	2002/10/21
	_	(monolithic adj microwave or	US-PGPUB;	08:15
		MMIC).ti,ab,clm.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	6	silver adj epoxy near12 (die or chip) and	USPAT;	2002/10/21
	1	(monolithic adj microwave or MMIC)	US-PGPUB;	08:21
			EPO; JPO;	
			DERWENT;	
<u></u>			IBM_TDB	

			T	
	16	solder near4 preform and MMIC	USPAT; US-PGPUB; EPO; JPO;	2002/10/21 08:21
			DERWENT; IBM TDB	
_	13	solder near4 preform and MMIC.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/21 08:31
	1	(radio-frequency or radio adj frequency or rf) adj (lid or cover) near15 (MMIC or monolithic adj microwave)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/21 08:34
_	1	(radio-frequency or radio adj frequency or rf or kovar) adj (lid or cover) near15 (MMIC or monolithic adj microwave)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/21 08:34
	2	(radio-frequency or radio adj frequency or rf or kovar) near4 (lid or cover) near15 (MMIC or monolithic adj microwave)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/21 09:03
-	158	isolation near3 (via or through-hole or through adj hole) and (chip or die).ti,ab,clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/21 09:05
_	20	isolation adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/21 09:05
_		isolation adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm. and (mmic or monolithic adj microwave)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:07
-	6	(insulation or isolation or insulating or isolating) adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm. and (mmic or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:11
_	47	,	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:12
-	1	isolation adj via.ti,ab,clm. and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/21 09:12
_	6	isolation adj via.ti,ab,clm. and (chip or die)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/21 09:17
_	1	(isolation adj via or isolation adj trench).ti,ab,clm. and (chip or die) and mmic	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:18
_	3097	mmic and sti or isolation adj trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:19

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